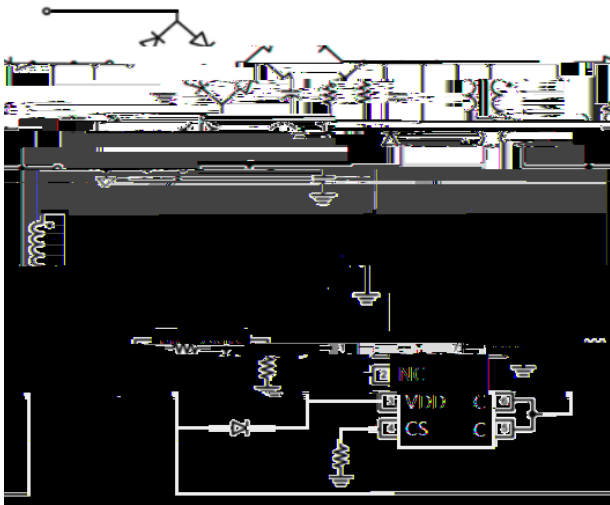


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/ Typical Application Circuit

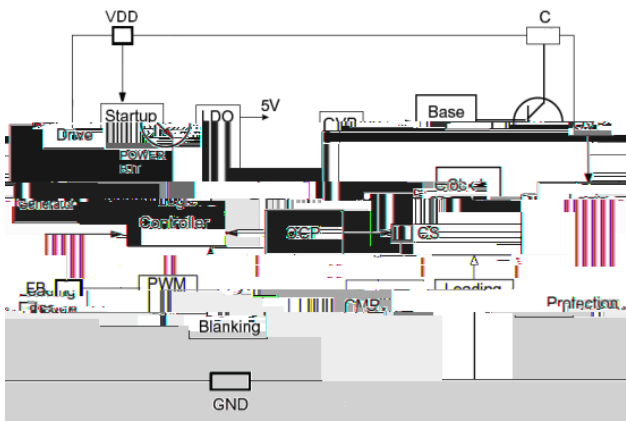


/ Pinning & Description



Pin Number	Pin Name	Description
1	FB	
2	NC	
3	VDD	
4	CS	
5 6	C	BJT
7	GND	

/ Block Diagram



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Note 1: If the device operating conditions over the maximum rating of the above-mentioned conditions, may cause permanent damage to the device. The above parameters is only part of the operating

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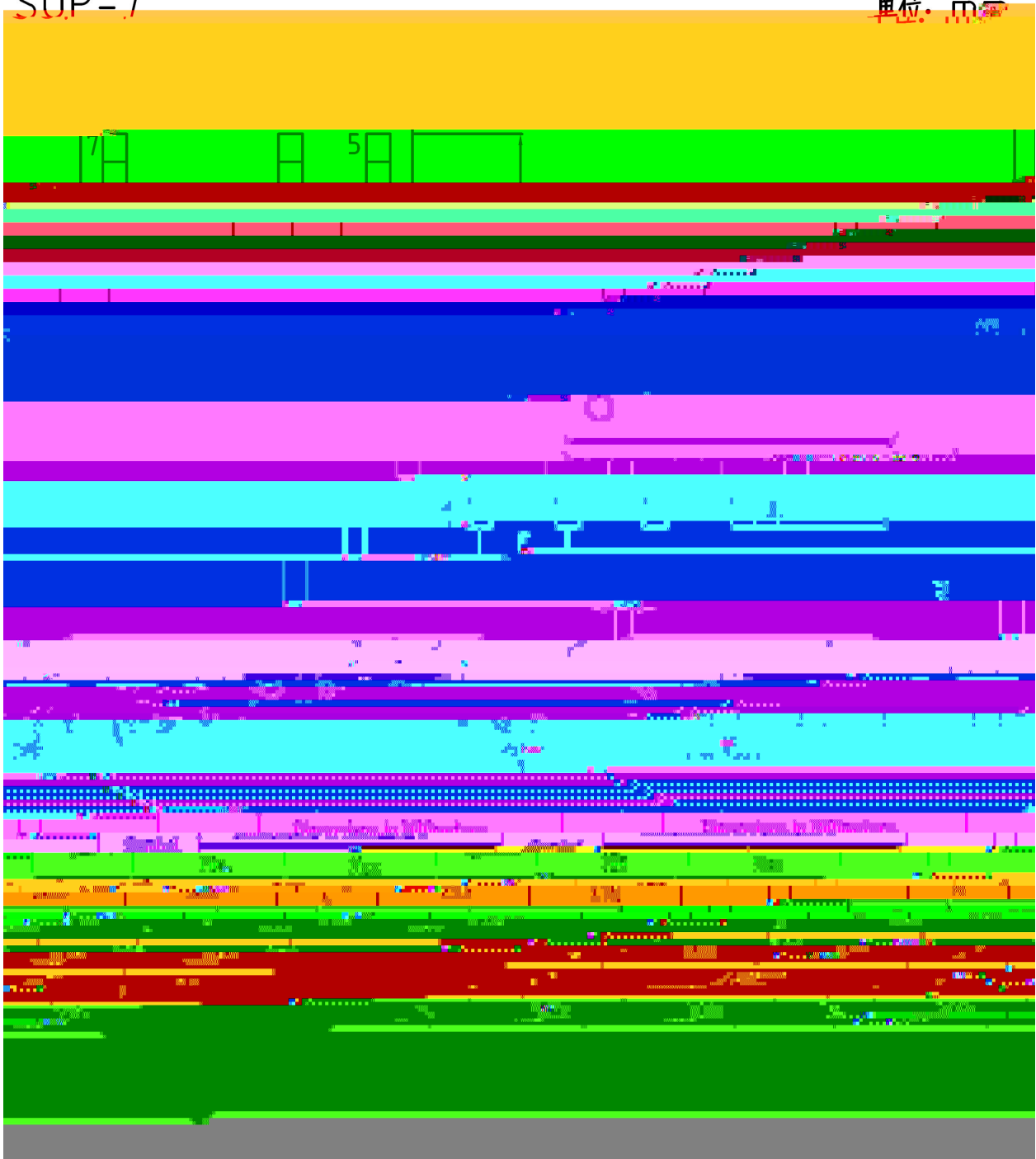
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Maximum Cable Drop Compensation (CDC) Current	$I_{\text{Cable_max}}$			45		uA
Current Sense Input Section (CS Pin)						
CS Input Leading Edge Blanking Time	T_{LEB}			350		ns
Minimum overcurrent protection threshold	$V_{\text{TH_OCPmin}}$			500		mV
Maximum overcurrent protection threshold	$V_{\text{TH_OCPmax}}$			550		mV
Power BJT Section (C Pin)						



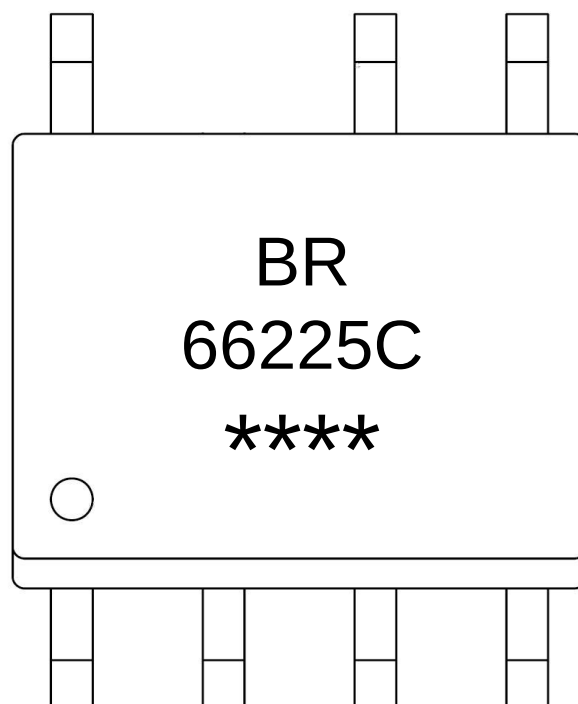
/ Package Dimensions

SOP-7

单位: mm



/ Marking Instructions



BR

66225C

66225D

66225E

****:

Note

BR

Company Code

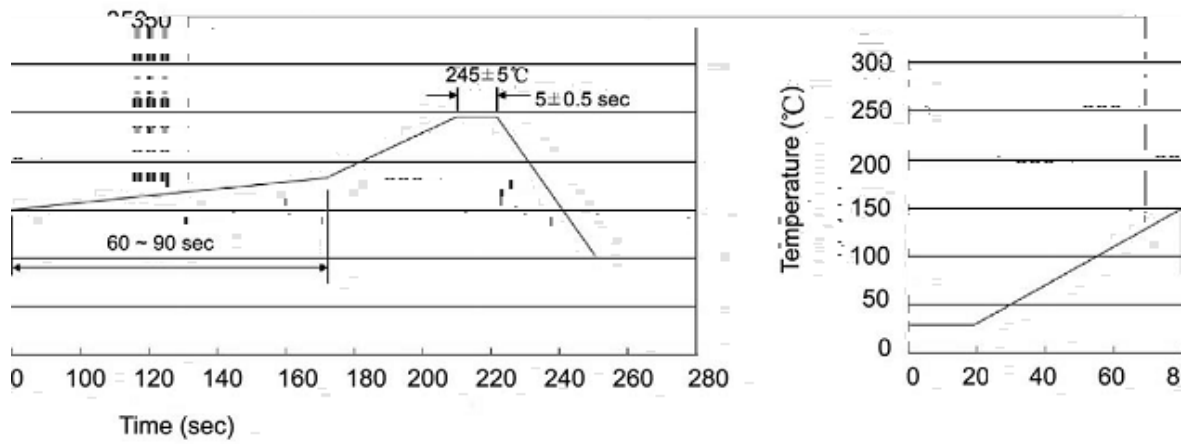
66225C

Product Type, or 66225D , or 66225E

****:

Lot No.Code,code change with Lot No.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|---------------------------------------|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type